

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1.-29. (Cancelled)

30. (Currently Amended) The ~~phosphonium compound~~ method as claimed in ~~claim 29~~ claim 44, wherein the THP⁺ salt is tetrakis (hydroxymethyl) phosphonium sulphate.

31. (Currently Amended) The ~~phosphonium compound~~ method as claimed in ~~claim 29~~ claim 44, wherein the ~~THP~~ THP⁺ salt is selected from the group consisting of tetrakis (hydroxymethyl) phosphonium chloride, tetrakis (hydroxymethyl) phosphonium phosphate, tetrakis (hydroxymethyl) phosphonium formate, tetrakis (hydroxymethyl) phosphonium acetate and tetrakis (hydroxymethyl) phosphonium oxalate.

32. (Currently Amended) The ~~phosphonium compound~~ method as claimed in ~~claim 29~~ claim 44, wherein the nitrogen containing compound is urea.

33. (Currently Amended) The ~~phosphonium compound~~ method as claimed in ~~claim 29~~ claim 44, wherein the nitrogen containing compound is melamine, guanidine or dicyandiamide.

34. (Currently Amended) The ~~phosphonium compound~~ method as claimed in ~~claim 29~~ claim 44, wherein the matrix substrate has a melting point of between from 20 50 to 70 °C[[,]] ~~optionally of 60 °C.~~

35.-36. (Cancelled)

37. (Currently Amended) The ~~phosphonium compound~~ method as claimed in ~~claim 35~~ claim 44, wherein the polyhydric compound is polyethylene glycol 8000.

38. - 41. (Cancelled)

42. (Currently Amended) The method as defined by claim 44,
wherein the industrial system is contacted with the A formulation comprising a
phosphonium compound as defined in claim 29 and embedded in the matrix
substrate together with one or more of the following: scale inhibitors, corrosion

inhibitors, additional biocides, demulsifiers, gas hydrate inhibitors, asphaltene inhibitors/dispersants, other surfactants, anti- foams/defoamers, fragrances, wax inhibitors, scale solvers, gelling agents, and oxygen scavengers.

43. (Currently Amended) The method as defined by claim 44,
wherein the phosphonium compound embedded in the matrix substrate is used in
the form of sticks/candles ~~Sticks/candles~~, beads, pellets, bricks, shavings, flakes or
~~prills comprising a phosphonium compound as defined in claim 29.~~

44. (New) A method for reducing the number of microorganisms or the amount of scale in an industrial system, said method comprising the step of contacting the industrial system with an effective amount of a phosphonium compound embedded in a matrix substrate, wherein the phosphonium compound is selected from the group consisting of tris (hydroxymethyl) phosphine (THP), a THP+ salt (tetrakis (hydroxymethyl) phosphonium salt), and a condensate of THP with a nitrogen containing compound selected from the group consisting of urea, melamine, guanidine and dicyandiamide, and wherein the matrix substrate is a polyhydric compound which is a polyethylene glycol having a molecular weight above 600, having a melting point of between 50° and 80°C and being soluble in water at a temperature of between 5° and 100°C.

45. (New) The method as claimed in claim 44, wherein the matrix substrate is soluble in water at a temperature of 20°C.

46. (New) The method as claimed in claim 34, wherein the matrix substrate has a melting point of 60°C.

47. (New) The method as claimed in claim 44, wherein the microorganisms are selected from the group consisting of sulfate reducing bacteria, heterotrophic bacteria and algae.

48. (New) The method as claimed in claim 44, wherein the industrial system is selected from the group consisting of storage vessels for water and fuel; fuel and gas pipelines; gas lift wells; water injection systems; and aqueous systems in paper production.